

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2739	(257/778).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/16 21:21
L2	1977	(257/786).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/16 21:04
L3	2153	(257/737).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/16 21:04
L4	21	1 and (interposer substrate board) with (vias holes throughholes through) with solder with columns	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:21
L5	5	2 and (interposer substrate board) with (vias holes throughholes through) with solder with columns	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:07
L6	15	3 and (interposer substrate board) with (vias holes throughholes through) with solder with columns	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:08
L7	131	((interposer substrate board) and (vias holes throughholes through) and solder and columns).clm.	US-PGPUB	OR	ON	2006/02/16 21:09
L8	461	interposer with capacit\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:15
L9	416	L8 and (IC integrated adj circuit chip die wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:15

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L10	324	L9 and (bump solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:15
L11	162	L9 and (bump solder)	USPAT	OR	ON	2006/02/16 21:15
L12	3	("5903050" "5937493" "6384468").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/16 21:15
L13	56	("5519576" "5672909" "5691568").PN. OR ("5903050"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/16 21:15
L14	37	("4225468" "4300115" "4332341" "4626804" "4654628" "4658234" "4712161" "4945399" "5216404" "5379190" "5539186" "5557502" "5621619" "5629838" "5635767" "5636099" "5661450" "5726485" "5729438" "5745334" "5760662" "5796587" "5870274" "5903050" "5923077" "5977863" "6005777" "6097277" "6103146" "6124634").PN. OR ("6326677"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/16 21:15
L15	61	teflon with elasticity with modul\$5	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/16 21:15
L16	0	teflon near2 "Young's" adj modulus	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/16 21:15
L17	0	teflon near2 Young\$3 adj modulus	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/16 21:15
L18	126436	teflon wiht Young\$3 adj modulus	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/16 21:15
L19	17	teflon with Young\$3 adj modulus	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/16 21:15
L20	962	silicon with Young\$3 adj modulus	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/16 21:15
L21	73	silicon near2 Young\$3 adj modulus	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/16 21:15
L22	21	("6222246").URPN.	USPAT	OR	ON	2006/02/16 21:15
L23	47129	layer near2 capacit\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:15

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L24	19790	L23 and (IC integrated adj circuit chip die wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:15
L25	27	interposer with L23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:15
L26	33490	film near2 capacit\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:15
L27	27	interposer with L26	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:15
L28	23321	substrate near2 capacit\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:15
L29	6743	substrate with L23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:15
L30	3802	L29 and (IC integrated adj circuit chip die wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:15
L31	200	interposer with capacit\$5	USPAT	OR	ON	2006/02/16 21:15
L32	1	capacitive adj layer with interposer	USPAT	OR	ON	2006/02/16 21:15
L33	3	capacitive adj layer with interposer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:15

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L34	5	capacitive near2 layer with interposer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:15
L35	55	("4202007" "4322778" "4328530" "4349862" "4489364" "4688151" "4744008" "4803595" "4811082" "4866507" "4926241").PN. OR ("5177594").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/16 21:15
L36	1	"5177594".PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/16 21:15
L37	1	L36 AND capac\$8	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/16 21:15
L38	55	("4202007" "4322778" "4328530" "4349862" "4489364" "4688151" "4744008" "4803595" "4811082" "4866507" "4926241").PN. OR ("5177594").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/16 21:15
L39	22208	motherboard	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:15
L40	32	motherboard with PCB WITH interposer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:16
L41	270	motherboard WITH interposer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:16
L42	104	motherboard WITH interposer	USPAT	OR	ON	2006/02/16 21:16
L43	0	motherboard WITH leve	USPAT	OR	ON	2006/02/16 21:16
L44	356	motherboard WITH level	USPAT	OR	ON	2006/02/16 21:16
L45	0	mother adj board WITH last with level	USPAT	OR	ON	2006/02/16 21:16
L46	8	mother adj board WITH last	USPAT	OR	ON	2006/02/16 21:16
L47	1502	motherboard and "257"\$.ccls.	USPAT	OR	ON	2006/02/16 21:16
L48	196	L47 and interposer	USPAT	OR	ON	2006/02/16 21:16

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L49	461	interposer with capacit\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:16
L50	416	L49 and (IC integrated adj circuit chip die wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:16
L51	324	L50 and (bump solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:16
L52	0	teflon near2 "Young's" adj modulus	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/16 21:16
L53	0	teflon near2 Young\$3 adj modulus	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/16 21:16
L54	126436	teflon wiht Young\$3 adj modulus	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/16 21:16
L55	962	silicon with Young\$3 adj modulus	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/16 21:16
L56	47129	layer near2 capacit\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:16
L57	19790	L56 and (IC integrated adj circuit chip die wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:16
L58	33490	film near2 capacit\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:16
L59	23321	substrate near2 capacit\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:16

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L60	6743	substrate with L56	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:16
L61	3802	L60 and (IC integrated adj circuit chip die wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:16
L62	1	capacitive adj layer with interposer	USPAT	OR	ON	2006/02/16 21:16
L63	3	capacitive adj layer with interposer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:16
L64	1	"5177594".PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/16 21:16
L65	22208	motherboard	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:16
L66	270	motherboard WITH interposer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:16
L67	0	motherboard WITH leve	USPAT	OR	ON	2006/02/16 21:16
L68	0	mother adj board WITH last with level	USPAT	OR	ON	2006/02/16 21:16
L69	1502	motherboard and "257"/\$.ccls.	USPAT	OR	ON	2006/02/16 21:16
L70	1	L64 AND capac\$8	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/16 21:16
L71	3	("5903050" "5937493" "6384468").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/16 21:16
L72	56	("5519576" "5672909" "5691568").PN. OR ("5903050").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/16 21:16

EAST Search History

L73	37	("4225468" "4300115" "4332341" "4626804" "4654628" "4658234" "4712161" "4945399" "5216404" "5379190" "5539186" "5557502" "5621619" "5629838" "5635767" "5636099" "5661450" "5726485" "5729438" "5745334" "5760662" "5796587" "5870274" "5903050" "5923077" "5977863" "6005777" "6097277" "6103146" "6124634").PN. OR ("6326677"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/16 21:16
L74	61	teflon with elasticity with modul\$5	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/16 21:16
L75	17	teflon with Young\$3 adj modulus	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/16 21:16
L76	73	silicon near2 Young\$3 adj modulus	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/16 21:16
L77	21	("6222246").URPN.	USPAT	OR	ON	2006/02/16 21:16
L78	27	interposer with L56	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:16
L79	27	interposer with L58	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:16
L80	5	capacitive near2 layer with interposer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:16
L81	55	("4202007" "4322778" "4328530" "4349862" "4489364" "4688151" "4744008" "4803595" "4811082" "4866507" "4926241").PN. OR ("5177594").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/16 21:16
L82	55	("4202007" "4322778" "4328530" "4349862" "4489364" "4688151" "4744008" "4803595" "4811082" "4866507" "4926241").PN. OR ("5177594").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/16 21:16

EAST Search History

L83	32	<i>motherboard with PCB WITH interposer</i>	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:16
L84	104	<i>motherboard WITH interposer</i>	USPAT	OR	ON	2006/02/16 21:16
L85	8	<i>mother adj board WITH last</i>	USPAT	OR	ON	2006/02/16 21:16
L86	162	<i>L50 and (bump solder)</i>	USPAT	OR	ON	2006/02/16 21:16
L87	200	<i>interposer with capacit\$5</i>	USPAT	OR	ON	2006/02/16 21:16
L88	196	<i>L69 and interposer</i>	USPAT	OR	ON	2006/02/16 21:16
L89	356	<i>motherboard WITH level</i>	USPAT	OR	ON	2006/02/16 21:16
L90	870	<i>(438/109).CCLS.</i>	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/16 21:21
L91	4	<i>90 and (interposer substrate board) with (vias holes throughholes through) with solder with columns</i>	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/16 21:21